27th IEEE International System-on-Chip Conference
September 2-5, 2014
Planet Hollywood Resort, Las Vegas, NV, USA

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Call For Papers

The IEEE SoC Conference (SOCC) is a premier forum for sharing advances in SoC technologies and applications in the areas of digital systems, circuit architectures, computing platforms, design methods, automations, test, and emerging technologies. SOCC2014 offers a three-day technical program including keynote and plenary speeches, oral and poster presentations, hot-topic panel sessions and tutorials, and exhibitions. This year the SOCC introduces a "Design Track" to encourage engineers to present their work and share their knowledge and experience on issues and practical solutions in the development of SoC designs. SOCC2014 also provides a high quality social events program, including a Las Vegas show, conference banquet, and a tour of the cavernous powerhouse of Hoover Dam hydro-electric plant. *Contact us:* info@ieee-socc.org.

Submission of Papers and Workshop/Tutorial/Special Session Proposals

Online paper submissions are in *pdf* format, limited to **six** double-column IEEE format pages. Paper submissions will go through a double-blind peer review process. The SOCC proceedings will be submitted to IEEE *Xplore®*. Workshop/tutorial proposals with title, a one-page summary, and speaker's short bio are submitted to the Tutorial Chair. ***Special session*** proposals may include title, topic rationale, organizer's short bio, and a list of contributed papers, which are submitted to the TPC Chairs. "***Design Track***" submissions require a two-page extended abstract which will be published on the SOCC website and in the program. For detailed formatting instructions and submission guidelines, please refer to www.ieee-socc.org.

SOCC Areas of Interest

Papers are invited which address new and previously unpublished results in the areas:

- ✦ Analog and Mixed−Signal Circuits and Systems
- ✦ Biomedical Circuits and Systems
- ✦ Wireline and Wireless Communication Circuits and Systems
- ✦ Digital Signal Processing (DSP) Circuits and Systems
- ✦ Low-Power, "Green" Circuits, Systems, and Design Methodologies
- ✦ Embedded Systems, Multi/Many Core Systems & Embedded Memory Technologies
- ✦ Network on Chip (NoC), Interconnects, and 3D−IC
- ✦ Reconfigurable and Programmable Circuits and Systems
- ✦ System Level Design Methodology and Tools
- ✦ Design for Testability and Manufacturability
- ✦ Design Verification
- ✦ Computing Platform Architectures

Key Dates

Special session proposal submission deadline:	March 10th, 2014
Regular paper submission deadline:	March 31st, 2014
Workshop/tutorial proposal submission deadline:	April 8th, 2014
Design Track extended abstract due:	April 14th, 2014
Notification of acceptance:	June 10th, 2014
Final camera−ready paper due:	June 30th, 2014